

RF Power Field Effect Transistors

N-Channel Enhancement-Mode Lateral MOSFETs

Designed for PCN and PCS base station applications with frequencies from 1900 to 2000 MHz. Suitable for TDMA, CDMA and multicarrier amplifier applications.

- Typical 2-Carrier N-CDMA Performance: $V_{DD} = 28$ Volts, $I_{DQ} = 850$ mA, $P_{out} = 18$ Watts Avg., Full Frequency Band, IS-95 CDMA (Pilot, Sync, Paging, Traffic Codes 8 Through 13) Channel Bandwidth = 1.2288 MHz. PAR = 9.8 dB @ 0.01% Probability on CCDF.
Power Gain — 14.5 dB
Drain Efficiency — 25.8%
IM3 @ 2.5 MHz Offset — -37 dBc in 1.2288 MHz Bandwidth
ACPR @ 885 kHz Offset — -51 dB in 30 kHz Bandwidth
- Capable of Handling 10:1 VSWR, @ 28 Vdc, 1960 MHz, 90 Watts CW Output Power

Features

- Characterized with Series Equivalent Large-Signal Impedance Parameters
- Internally Matched for Ease of Use
- Qualified Up to a Maximum of 32 V_{DD} Operation
- Integrated ESD Protection
- Lower Thermal Resistance Package
- Low Gold Plating Thickness on Leads, 40 μ m Nominal.
- RoHS Compliant
- In Tape and Reel. R3 Suffix = 250 Units per 56 mm, 13 inch Reel.

MRF5S19090HR3
MRF5S19090HSR3

1930-1990 MHz, 18 W AVG., 28 V
2 x N-CDMA
LATERAL N-CHANNEL
RF POWER MOSFETs

CASE 465-06, STYLE 1
NI-780
MRF5S19090HR3

CASE 465A-06, STYLE 1
NI-780S
MRF5S19090HSR3

Table 1. Maximum Ratings

Rating	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	-0.5, +65	Vdc
Gate-Source Voltage	V_{GS}	-0.5, +15	Vdc
Total Device Dissipation @ $T_C = 25^\circ\text{C}$ Derate above 25°C	P_D	266 1.52	W W/ $^\circ\text{C}$
Storage Temperature Range	T_{stg}	- 65 to +200	$^\circ\text{C}$
Case Operating Temperature	T_C	150	$^\circ\text{C}$
Operating Junction Temperature	T_J	200	$^\circ\text{C}$

Table 2. Thermal Characteristics

Characteristic	Symbol	Value (1,2)	Unit
Thermal Resistance, Junction to Case Case Temperature 80°C , 65 W CW Case Temperature 78°C , 18 W CW	$R_{\theta JC}$	0.66 0.68	$^\circ\text{C}/\text{W}$

1. MTTF calculator available at <http://www.freescale.com/rf>. Select Tools/Software/Application Software/Calculators to access the MTTF calculators by product.
2. Refer to AN1955, *Thermal Measurement Methodology of RF Power Amplifiers*. Go to <http://www.freescale.com/rf>. Select Documentation/Application Notes - AN1955.

Table 3. ESD Protection Characteristics

Test Conditions	Class
Human Body Model	1 (Minimum)
Machine Model	M3 (Minimum)
Charge Device Model	C7 (Minimum)

Table 4. Electrical Characteristics ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
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Off Characteristics

Zero Gate Voltage Drain Leakage Current ($V_{DS} = 65\text{ Vdc}$, $V_{GS} = 0\text{ Vdc}$)	I_{DSS}	—	—	10	μAdc
Zero Gate Voltage Drain Leakage Current ($V_{DS} = 28\text{ Vdc}$, $V_{GS} = 0\text{ Vdc}$)	I_{DSS}	—	—	1	μAdc
Gate-Source Leakage Current ($V_{GS} = 5\text{ Vdc}$, $V_{DS} = 0\text{ Vdc}$)	I_{GSS}	—	—	1	μAdc

On Characteristics (DC)

Gate Threshold Voltage ($V_{DS} = 10\text{ Vdc}$, $I_D = 200\text{ }\mu\text{Adc}$)	$V_{GS(th)}$	2.5	2.7	3.5	Vdc
Gate Quiescent Voltage ($V_{DS} = 28\text{ Vdc}$, $I_D = 850\text{ mAdc}$)	$V_{GS(Q)}$	—	3.7	—	Vdc
Drain-Source On-Voltage ($V_{GS} = 10\text{ Vdc}$, $I_D = 2\text{ Adc}$)	$V_{DS(on)}$	—	0.26	—	Vdc
Forward Transconductance ($V_{DS} = 10\text{ Vdc}$, $I_D = 2\text{ Adc}$)	g_{fs}	—	5	—	S

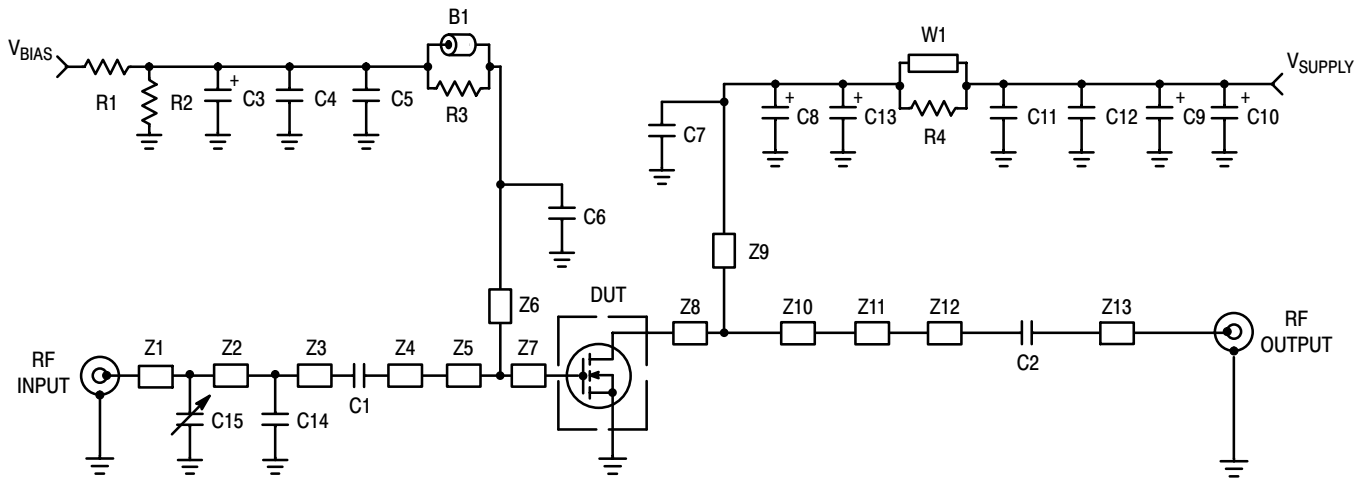
Dynamic Characteristics ⁽¹⁾

Reverse Transfer Capacitance ($V_{DS} = 28\text{ Vdc} \pm 30\text{ mV(rms)ac}$ @ 1 MHz, $V_{GS} = 0\text{ Vdc}$)	C_{rss}	—	1.7	—	pF
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Functional Tests (In Freescale Test Fixture, 50 ohm system) $V_{DD} = 28\text{ Vdc}$, $I_{DQ} = 850\text{ mA}$, $P_{out} = 18\text{ W Avg.}$, $f_1 = 1930\text{ MHz}$, $f_2 = 1932.5\text{ MHz}$ and $f_1 = 1987.5\text{ MHz}$, $f_2 = 1990\text{ MHz}$, 2-Carrier N-CDMA, 1.2288 MHz Channel Bandwidth Carriers. ACPR measured in 30 kHz Channel Bandwidth @ $\pm 885\text{ kHz}$ Offset. IM3 measured in 1.2288 MHz Channel Bandwidth @ $\pm 2.5\text{ MHz}$ Offset. PAR = 9.8 dB @ 0.01% Probability on CCDF.

Power Gain	G_{ps}	13.5	14.5	—	dB
Drain Efficiency	η_D	24	25.8	—	%
Intermodulation Distortion	IM3	—	-37	-35	dBc
Adjacent Channel Power Ratio	ACPR	—	-51	-48	dBc
Input Return Loss	IRL	—	-14.5	-9	dB

1. Part is internally matched both on input and output.

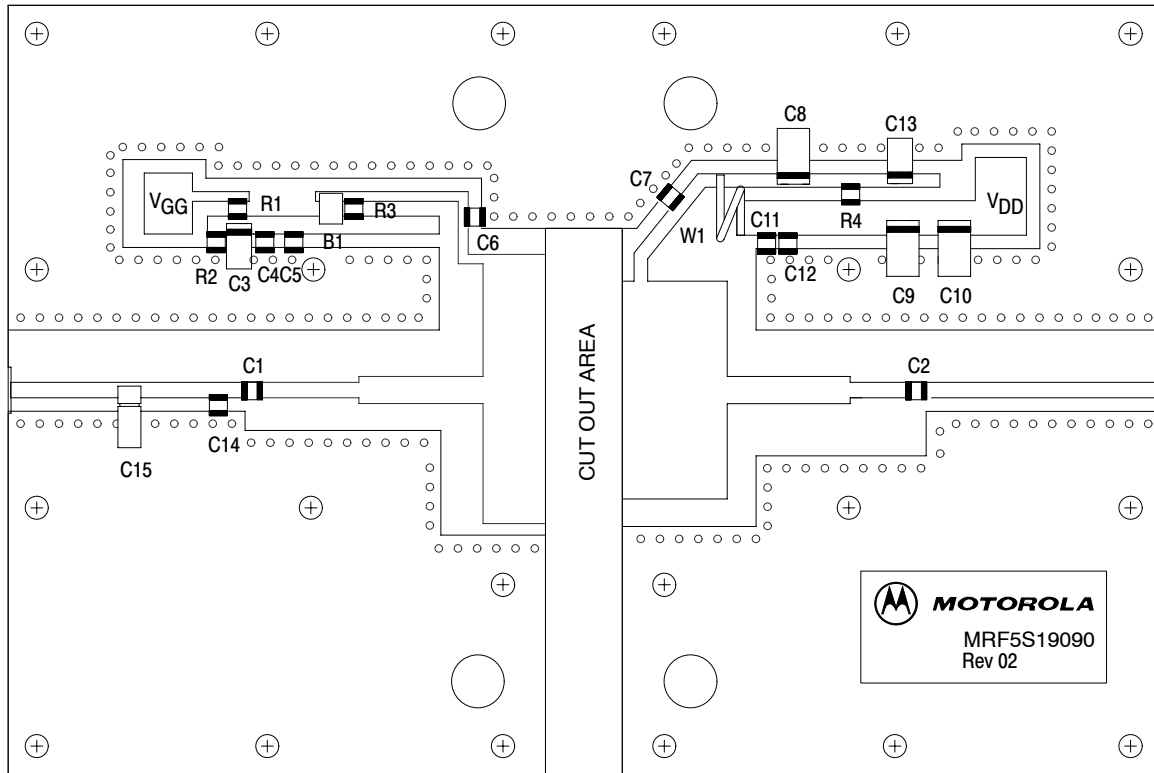


Z1	0.140" x 0.080" Microstrip	Z8	0.091" x 1.133" Microstrip
Z2	0.450" x 0.080" Microstrip	Z9	0.542" x 0.071" Microstrip
Z3	0.140" x 0.080" Microstrip	Z10	0.450" x 1.133" Microstrip
Z4	0.525" x 0.080" Microstrip	Z11	0.640" x 0.141" Microstrip
Z5	0.636" x 0.141" Microstrip	Z12	0.316" x 0.080" Microstrip
Z6	0.340" x 0.050" Microstrip	Z13	1.209" x 0.080" Microstrip
Z7	0.320" x 1.401" Microstrip	PCB	Arlon GX-0300-55-22, 0.030", $\epsilon_r = 2.55$

Figure 1. MRF5S19090HR3(HSR3) Test Circuit Schematic

Table 5. MRF5S19090HR3(HSR3) Test Circuit Component Designations and Values

Part	Description	Part Number	Manufacturer
B1	Short RF Bead	95F786	Newark
C1	22 pF Chip Capacitor	100B220CP 500X	ATC
C2	10 pF Chip Capacitor	100B100CP 500X	ATC
C3, C13	1 μ F, 50 V SMT Tantalum Capacitors	T494C105(1)050AS	Kemet
C4, C12	0.1 μ F Chip Capacitors	CDR33BX104AKWS	Kemet
C5, C11	1k pF Chip Capacitors	100B102JP 500X	ATC
C6, C7	4.3 pF Chip Capacitors	100B4R3JP 500X	ATC
C8	10 μ F, 35 V SMT Tantalum Capacitor	T494D106(1)035AS	Kemet
C9, C10	22 μ F, 35 V SMT Tantalum Capacitors	T494X226(1)035AS	Kemet
C14	2.7 pF Chip Capacitor	100B2.7BP 500X	ATC
C15	0.6 – 4.5 Gigatrim Variable Capacitor	44F3358	Newark
R1	1 k Ω Chip Resistor	D5534M07B1K00R	Newark
R2	560 k Ω Chip Resistor	CR1206 564JT	Newark
R3, R4	12 Ω Chip Resistors	RM73B2B120JT	Garrett Electronics
W1	1 turn 14 gauge wire		



Freescall has begun the transition of marking Printed Circuit Boards (PCBs) with the Freescall Semiconductor signature/logo. PCBs may have either Motorola or Freescall markings during the transition period. These changes will have no impact on form, fit or function of the current product.

Figure 2. MRF5S19090HR3(HSR3) Test Circuit Component Layout

TYPICAL CHARACTERISTICS

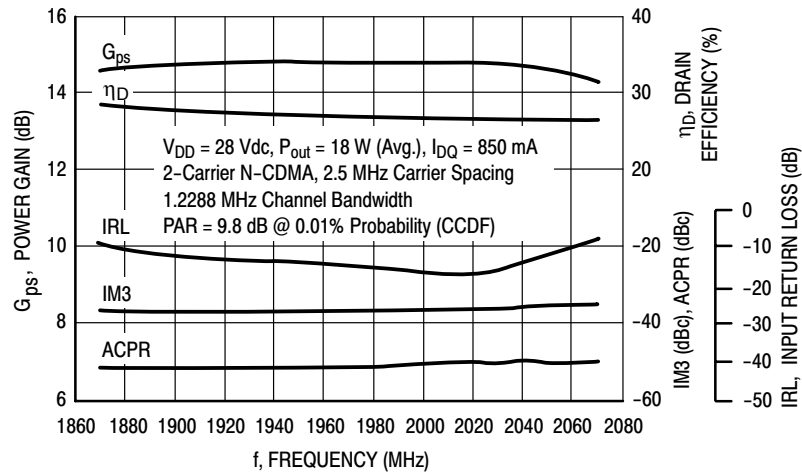


Figure 3. 2-Carrier N-CDMA Broadband Performance

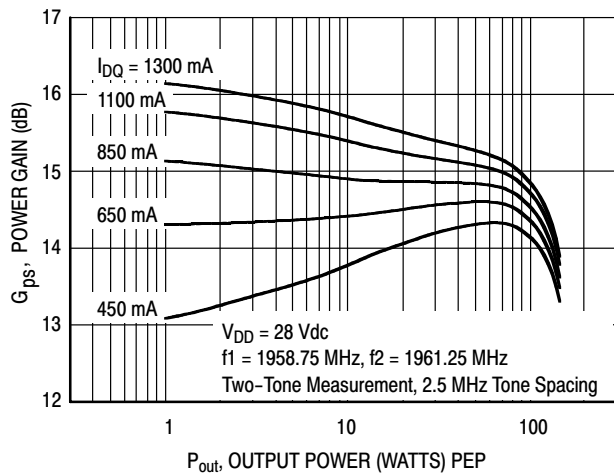


Figure 4. Two-Tone Power Gain versus Output Power

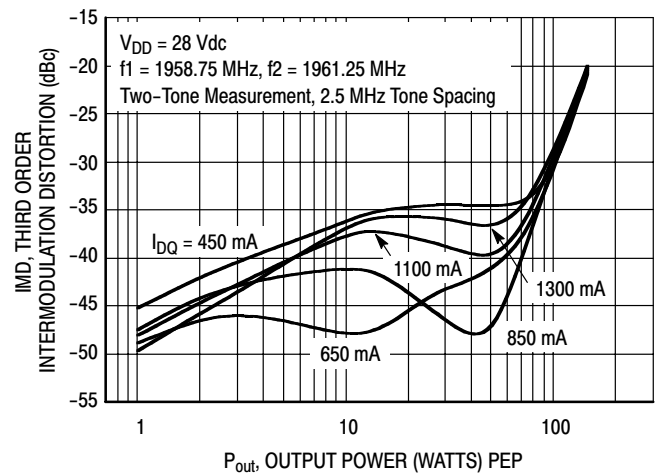


Figure 5. Third Order Intermodulation Distortion versus Output Power

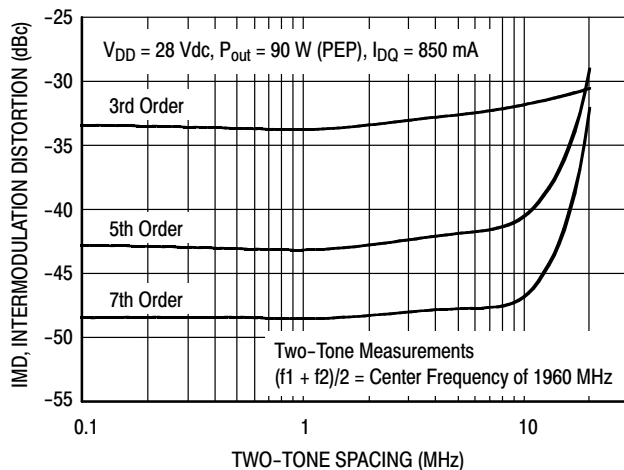


Figure 6. Intermodulation Distortion Products versus Tone Spacing

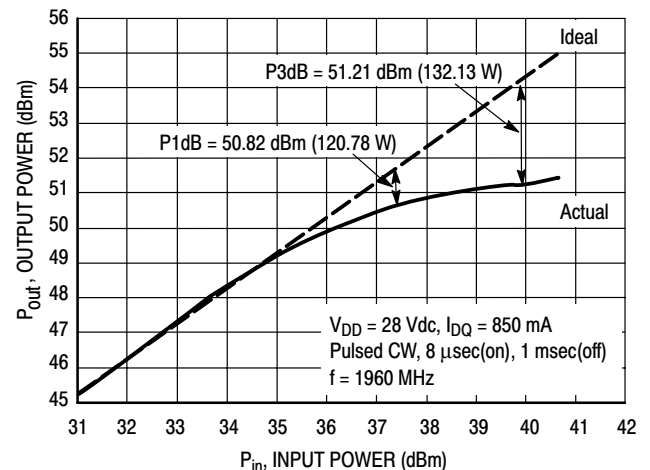


Figure 7. Pulse CW Output Power versus Input Power

MRF5S19090HR3 MRF5S19090HSR3

TYPICAL CHARACTERISTICS

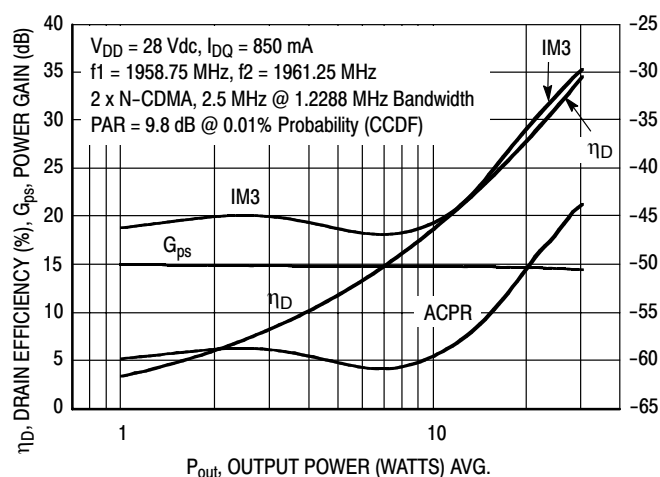
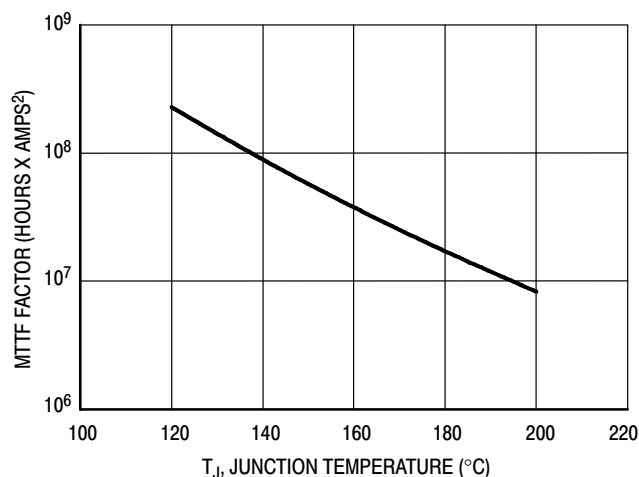


Figure 8. 2-Carrier N-CDMA ACPR, IM3, Power Gain and Drain Efficiency versus Output Power



This above graph displays calculated MTTF in hours x ampere² drain current. Life tests at elevated temperatures have correlated to better than $\pm 10\%$ of the theoretical prediction for metal failure. Divide MTTF factor by I_{DQ}^2 for MTBF in a particular application.

Figure 9. MTTF Factor versus Junction Temperature

N-CDMA TEST SIGNAL

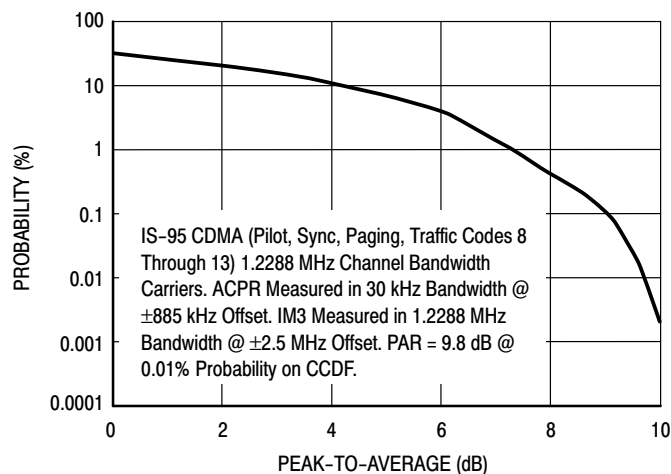


Figure 10. 2-Carrier CCDF N-CDMA

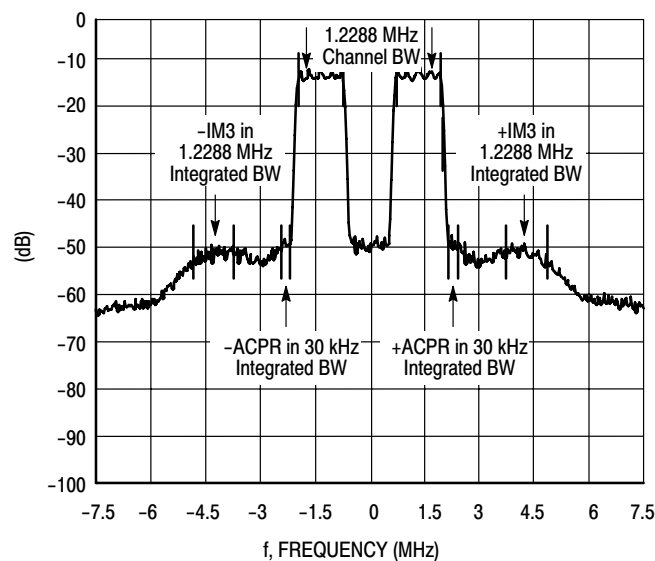
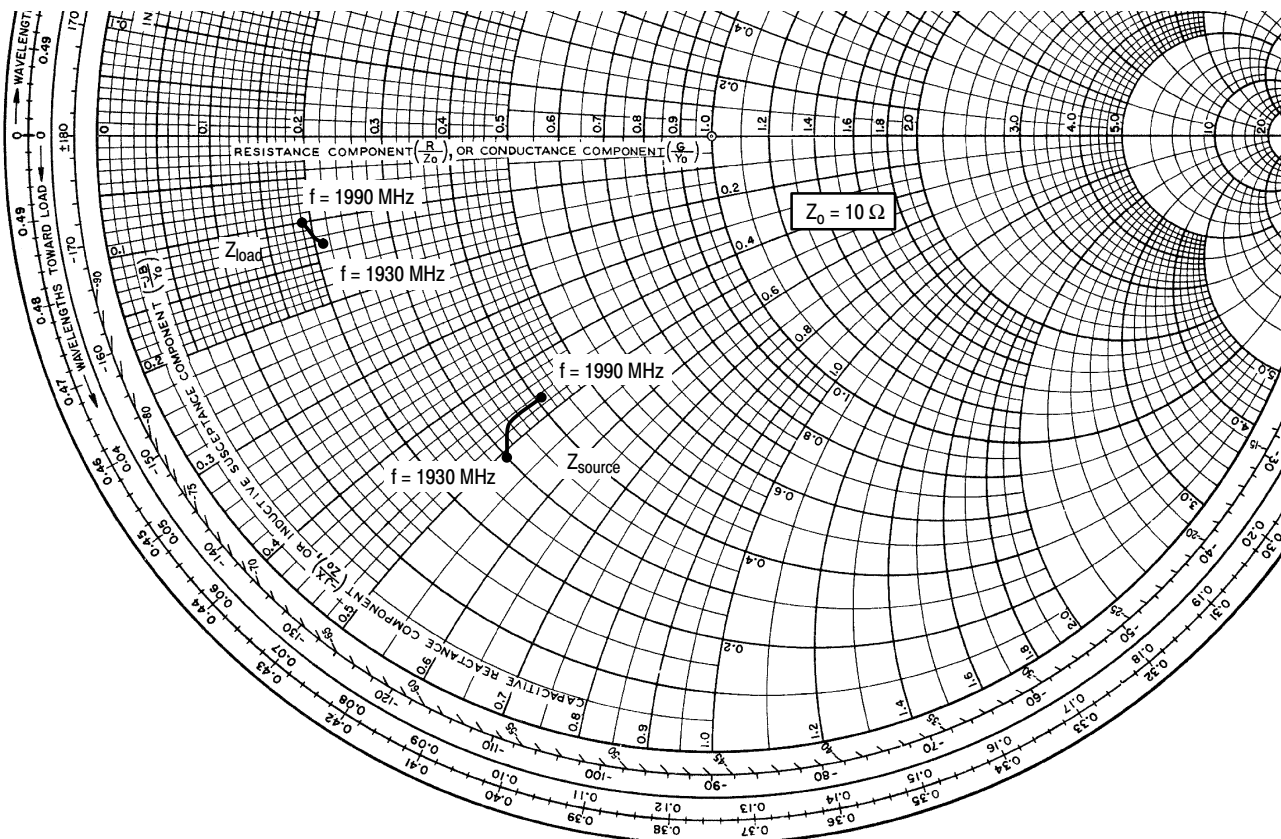


Figure 11. 2-Carrier N-CDMA Spectrum



$V_{DD} = 28 \text{ V}$, $I_{DQ} = 850 \text{ mA}$, $P_{out} = 18 \text{ W Avg.}$

f MHz	Z_{source} Ω	Z_{load} Ω
1930	$2.98 - j5.12$	$2.07 - j1.31$
1960	$3.36 - j4.65$	$2.02 - j1.18$
1990	$4.06 - j4.64$	$1.93 - j1.01$

Z_{source} = Test circuit impedance as measured from gate to ground.

Z_{load} = Test circuit impedance as measured from drain to ground.

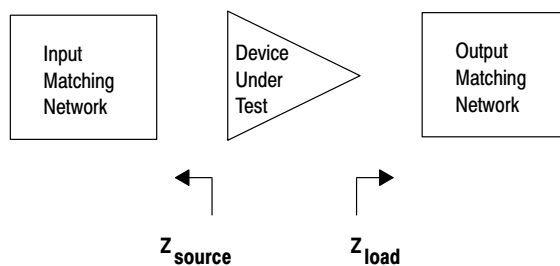


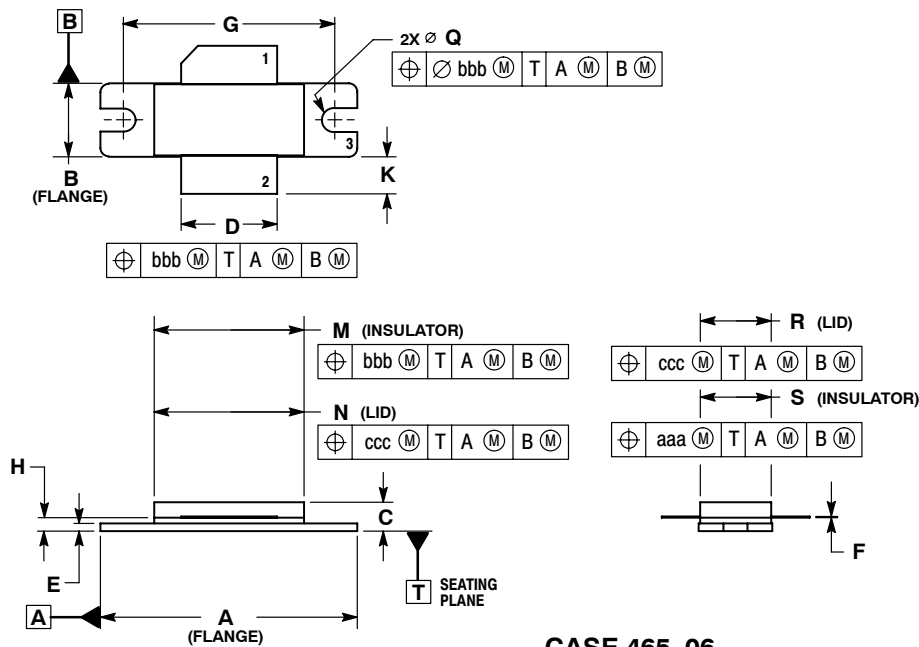
Figure 12. Series Equivalent Source and Load Impedance

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PACKAGE DIMENSIONS



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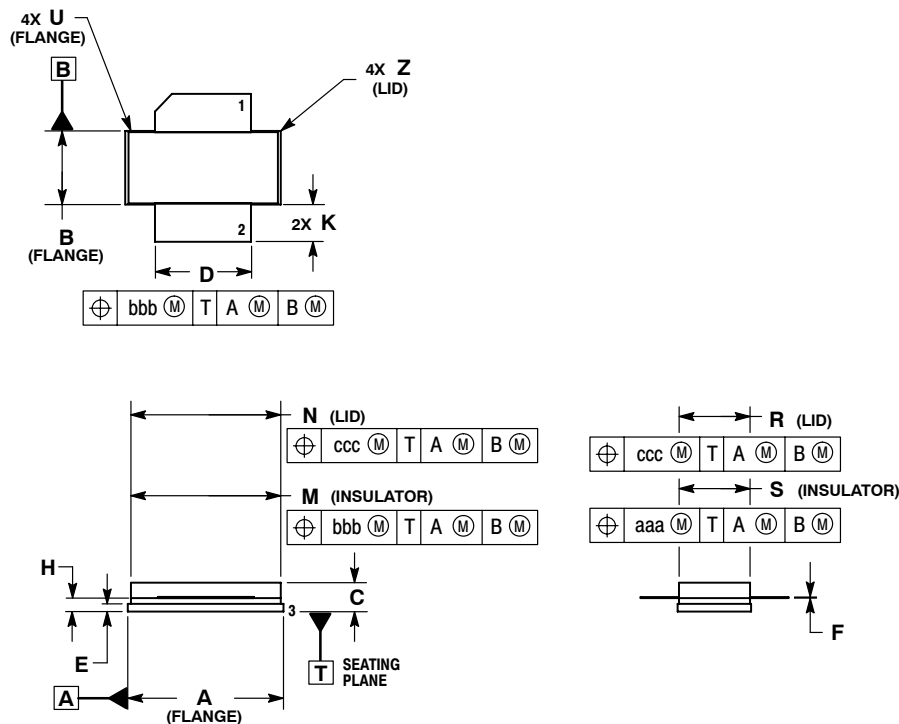
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1994.
2. CONTROLLING DIMENSION: INCH.
3. DELETED
4. DIMENSION H IS MEASURED 0.030 (0.762) AWAY FROM PACKAGE BODY.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.335	1.345	33.91	34.16
B	0.380	0.390	9.65	9.91
C	0.125	0.170	3.18	4.32
D	0.495	0.505	12.57	12.83
E	0.035	0.045	0.89	1.14
F	0.003	0.006	0.08	0.15
G	1.100 BSC		27.94 BSC	
H	0.057	0.067	1.45	1.70
K	0.170	0.210	4.32	5.33
M	0.774	0.786	19.66	19.96
N	0.772	0.788	19.60	20.00
Q	$\varnothing$ 1.18	$\varnothing$ 1.38	$\varnothing$ 3.00	$\varnothing$ 3.51
R	0.365	0.375	9.27	9.53
S	0.365	0.375	9.27	9.52
aaa	0.005 REF		0.127 REF	
bbb	0.010 REF		0.254 REF	
ccc	0.015 REF		0.381 REF	

STYLE 1:

1. DRAIN
2. GATE
3. SOURCE

**CASE 465-06
ISSUE G
NI-780
MRF5S19090HR3**



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1994.
2. CONTROLLING DIMENSION: INCH.
3. DELETED
4. DIMENSION H IS MEASURED 0.030 (0.762) AWAY FROM PACKAGE BODY.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.805	0.815	20.45	20.70
B	0.380	0.390	9.65	9.91
C	0.125	0.170	3.18	4.32
D	0.495	0.505	12.57	12.83
E	0.035	0.045	0.89	1.14
F	0.003	0.006	0.08	0.15
H	0.057	0.067	1.45	1.70
K	0.170	0.210	4.32	5.33
M	0.774	0.786	19.61	20.02
N	0.772	0.788	19.61	20.02
R	0.365	0.375	9.27	9.53
S	0.365	0.375	9.27	9.52
U	---	0.040	---	1.02
Z	---	0.030	---	0.76
aaa	0.005 REF		0.127 REF	
bbb	0.010 REF		0.254 REF	
ccc	0.015 REF		0.381 REF	

STYLE 1:

1. DRAIN
2. GATE
5. SOURCE

**CASE 465A-06
ISSUE H
NI-780S
MRF5S19090HSR3**

MRF5S19090HR3 MRF5S19090HSR3

How to Reach Us:

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Freescale Semiconductor
Technical Information Center, CH370
1300 N. Alma School Road
Chandler, Arizona 85224
+1-800-521-6274 or +1-480-768-2130
support@freescale.com

Europe, Middle East, and Africa:

Freescale Halbleiter Deutschland GmbH
Technical Information Center
Schatzbogen 7
81829 Muenchen, Germany
+44 1296 380 456 (English)
+46 8 52200080 (English)
+49 89 92103 559 (German)
+33 1 69 35 48 48 (French)
support@freescale.com

Japan:

Freescale Semiconductor Japan Ltd.
Headquarters
ARCO Tower 15F
1-8-1, Shimo-Meguro, Meguro-ku,
Tokyo 153-0064
Japan
0120 191014 or +81 3 5437 9125
support.japan@freescale.com

Asia/Pacific:

Freescale Semiconductor Hong Kong Ltd.
Technical Information Center
2 Dai King Street
Tai Po Industrial Estate
Tai Po, N.T., Hong Kong
+800 2666 8080
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